74HC74; 74HCT74Dual D-type flip-flop with set and reset; positive edge-triggerRev. 4 - 27 August 2012Product data sheet

### 1. General description

The 74HC74 and 74HC774 are dual positive edge triggered D-type flip-flop. They have individual data (nD), clock (nCP), set (nSD) and reset (nRD) inputs, and complementary nQ and nQ outputs. Data at the nD-input, that meets the set-up and hold time requirements on the LOW-to-HIGH clock transition, is stored in the flip-flop and appears at the nQ output. Schmitt-trigger action in the clock input, makes the circuit highly tolerant to slower clock rise and fall times. Inputs include clamp diodes that enable the use of current limiting resistors to interface inputs to voltages in excess of  $V_{CC}$ .

### 2. Features and benefits

- Input levels:
  - For 74HC74: CMOS level
  - For 74HCT74: TTL level
- Symmetrical output impedance
- Low power dissipation
- High noise immunity
- Balanced propagation delays
- Specified in compliance with JEDEC standard no. 7A
- ESD protection:
  - HBM JESD22-A114F exceeds 2000 V
  - MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from -40 °C to +85 °C and from -40 °C to +125 °C

## 3. Ordering information

### Table 1.Ordering information

Type number	Package									
	Temperature range	Name	Description	Version						
74HC74N	-40 °C to +125 °C	DIP14	plastic dual in-line package; 14 leads (300 mil)	SOT27-1						
74HCT74N										
74HC74D	–40 °C to +125 °C	SO14	plastic small outline package; 14 leads; body width	SOT108-						
74HCT74D			3.9 mm							
74HC74DB	–40 °C to +125 °C	SSOP14	plastic shrink small outline package; 14 leads; body	SOT337-1						
74HCT74DB			width 5.3 mm							



### Dual D-type flip-flop with set and reset; positive edge-trigger

Type number	Package							
	Temperature range	Name	Description	Version				
74HC74PW	–40 °C to +125 °C	TSSOP14	plastic thin shrink small outline package; 14 leads;	SOT402-1				
74HCT74PW			body width 4.4 mm					
74HC74BQ	–40 °C to +125 °C	DHVQFN14	plastic dual in-line compatible thermal enhanced very	SOT762-1				
74HCT74BQ			thin quad flat package; no leads; 14 terminals; body $2.5 \times 3 \times 0.85$ mm					

#### Table 1. Ordering information ...continued

## 4. Functional diagram





Dual D-type flip-flop with set and reset; positive edge-trigger

## 5. Pinning information

### 5.1 Pinning



### 5.2 Pin description

Table 2.	Pin description	
Symbol	Pin	Description
1 <mark>R</mark> D	1	asynchronous reset-direct input (active LOW)
1D	2	data input
1CP	3	clock input (LOW-to-HIGH, edge-triggered)
1 <mark>S</mark> D	4	asynchronous set-direct input (active LOW)
1Q	5	output
1 <mark>Q</mark>	6	complement output
GND	7	ground (0 V)
2 <mark>Q</mark>	8	complement output
2Q	9	output
2 <mark>S</mark> D	10	asynchronous set-direct input (active LOW)
2CP	11	clock input (LOW-to-HIGH, edge-triggered)
2D	12	data input
2RD	13	asynchronous reset-direct input (active LOW)
V <sub>CC</sub>	14	supply voltage

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Dual D-type flip-flop with set and reset; positive edge-trigger

## 6. Functional description

Table 3.	Function table <sup>[1]</sup>										
Input							Output				
n <mark>S</mark> D		nRD	1	nCP		nD		nQ		nQ	
L		Н		Х		Х		Н		L	
Н		L		Х		Х		L		Н	
L		L		Х		Х		Н		Н	

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care.

#### Table 4.Function table<sup>[1]</sup>

Input		Output			
n <mark>S</mark> D	nRD	nCP	nD	nQ <sub>n+1</sub>	n <mark>Q</mark> n+1
Н	Н	↑	L	L	Н
Н	Н	↑	Н	Н	L

[1] H = HIGH voltage level; L = LOW voltage level; ↑ = LOW-to-HIGH transition; Q<sub>n+1</sub> = state after the next LOW-to-HIGH CP transition; X = don't care.

### 7. Limiting values

#### Table 5.Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

					,
Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+7	V
I <sub>IK</sub>	input clamping current	$V_{\rm I}$ < –0.5 V or $V_{\rm I}$ > $V_{\rm CC}$ + 0.5 V	-	±20	mA
I <sub>OK</sub>	output clamping current	$V_{\rm O}$ < –0.5 V or $V_{\rm O}$ > $V_{\rm CC}$ + 0.5 V	-	±20	mA
lo	output current	$V_{\rm O} = -0.5$ V to (V <sub>CC</sub> + 0.5 V)	-	±25	mA
I <sub>CC</sub>	supply current		-	+100	mA
I <sub>GND</sub>	ground current		-100	-	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
P <sub>tot</sub>	total power dissipation	DIP14 package	<u>[1]</u> _	750	mW
		SO14, (T)SSOP14 and DHVQFN14 packages	<u>[1]</u> -	500	mW

For DIP14 package: P<sub>tot</sub> derates linearly with 12 mW/K above 70 °C.
 For SO14 package: P<sub>tot</sub> derates linearly with 8 mW/K above 70 °C.
 For (T)SSOP14 packages: P<sub>tot</sub> derates linearly with 5.5 mW/K above 60 °C.
 For DHVQFN14 packages: P<sub>tot</sub> derates linearly with 4.5 mW/K above 60 °C.

Dual D-type flip-flop with set and reset; positive edge-trigger

## 8. Recommended operating conditions

### Table 6. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions		74HC74			74HCT74	4	Unit
			Min	Тур	Max	Min	Тур	Max	
V <sub>CC</sub>	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
VI	input voltage		0	-	V <sub>CC</sub>	0	-	$V_{CC}$	V
Vo	output voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
T <sub>amb</sub>	ambient temperature		-40	+25	+125	-40	+25	+125	°C
$\Delta t / \Delta V$	input transition rise and fall rate	$V_{CC} = 2.0 V$	-	-	625	-	-	-	ns/V
		$V_{CC} = 4.5 V$	-	1.67	139	-	1.67	139	ns/V
		$V_{CC} = 6.0 V$	-	-	83	-	-	-	ns/V

## 9. Static characteristics

#### Table 7. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T <sub>amb</sub> =	-40 °C to	+85 °C	T <sub>amb</sub> = -40 °	C to +125 °C	Unit
			Min	Typ <mark>[1]</mark>	Max	Min	Мах	
74HC74								
V <sub>IH</sub>	HIGH-level	$V_{CC} = 2.0 V$	1.5	1.2	-	1.5	-	V
	input voltage	$V_{CC} = 4.5 V$	3.15	2.4	-	3.15	-	V
		$V_{CC} = 6.0 V$	4.2	3.2	-	4.2	-	V
V <sub>IL</sub>	LOW-level	$V_{CC} = 2.0 V$	-	0.8	0.5	-	0.5	V
	input voltage	$V_{CC} = 4.5 V$	-	2.1	1.35	-	1.35	V
		$V_{CC} = 6.0 V$	-	2.8	1.8	-	1.8	V
V <sub>он</sub>	HIGH-level	$V_{I} = V_{IH} \text{ or } V_{IL}$						
	output voltage	$I_{O} = -4.0 \text{ mA}; V_{CC} = 4.5 \text{ V}$	3.84	4.32	-	3.7	-	V
		$I_{O} = -5.2 \text{ mA}; V_{CC} = 6.0 \text{ V}$	5.34	5.81	-	5.2	-	V
V <sub>OL</sub>	LOW-level	$V_{I} = V_{IH} \text{ or } V_{IL}$						
	output voltage	$I_{O}$ = 4.0 mA; $V_{CC}$ = 4.5 V	-	0.15	0.33	-	0.4	V
		$I_{O} = 5.2 \text{ mA}; V_{CC} = 6.0 \text{ V}$	-	0.16	0.33	-	0.4	V
I	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 6.0 V$	-	-	±1.0	-	±1.0	μA
lcc	supply current		-	-	40	-	80	μA
CI	input capacitance			3.5				pF
74HCT7	4							
VIH	HIGH-level input voltage	$V_{CC}$ = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	$V_{CC}$ = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	V

## 74HC74; 74HCT74

### Dual D-type flip-flop with set and reset; positive edge-trigger

#### T<sub>amb</sub> = -40 °C to +85 °C Symbol Parameter Conditions $T_{amb} = -40 \text{ °C to } +125 \text{ °C}$ Unit Min Typ[1] Max Min Max **HIGH-level** $V_I = V_{IH} \text{ or } V_{IL}; V_{CC} = 4.5 \text{ V}$ Vон output voltage $I_{O} = -4 \text{ mA}$ 3.84 4.32 3.7 V -- $V_{OL}$ LOW-level $V_I = V_{IH}$ or $V_{IL}$ ; $V_{CC} = 4.5 V$ output voltage $I_{O} = 4.0 \text{ mA}$ 0.15 0.33 0.4 V -\_ $V_I = V_{CC}$ or GND; input leakage I<sub>I</sub> \_ -±1.0 - $\pm 1.0$ μA $V_{CC} = 5.5 V$ current supply current $V_I = V_{CC}$ or GND; $I_O = 0$ A; 40 80 $I_{CC}$ μΑ \_ -- $V_{CC} = 5.5 V$ additional $V_{I} = V_{CC} - 2.1 V;$ $\Delta I_{CC}$ other inputs at V<sub>CC</sub> or GND; supply current $V_{CC} = 4.5 V$ to 5.5 V; $I_0 = 0 A$ per input pin; nD, nRD 70 315 343 μΑ -inputs per input pin; nSD, nCP 80 360 392 \_ μΑ input C input 3.5 рF capacitance

### Table 7. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

[1] All typical values are measured at  $T_{amb} = 25 \ ^{\circ}C$ .

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Dual D-type flip-flop with set and reset; positive edge-trigger

## **10.** Dynamic characteristics

#### Table 8. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V);  $C_L = 50 \text{ pF}$  unless otherwise specified; for test circuit see Figure 9.

Symbol	Parameter	Conditions		Tamb	= -40 °C to	• +85 °C	T <sub>amb</sub> = -40	°C to +125 °C	Unit
				Min	Typ[1]	Мах	Min	Max	
74HC74									
t <sub>pd</sub>	propagation delay	nCP to nQ, n <mark>Q</mark> ; see <u>Figure 7</u>	[2]						
		$V_{CC} = 2.0 V$		-	47	220	-	265	ns
		$V_{CC} = 4.5 V$		-	17	44	-	53	ns
		$V_{CC} = 5 \text{ V}; \text{ C}_{L} = 15 \text{ pF}$		-	14	-	-	-	ns
		$V_{CC} = 6.0 V$		-	14	37	-	45	ns
		nSD to nQ, nQ; see Figure 8	[2]						
		$V_{CC} = 2.0 V$		-	50	250	-	300	ns
		$V_{CC} = 4.5 V$		-	18	50	-	60	ns
		$V_{CC} = 5 \text{ V}; \text{ C}_{L} = 15 \text{ pF}$		-	15	-	-	-	ns
		$V_{CC} = 6.0 V$		-	14	43	-	51	ns
		nRD to nQ, nQ; see Figure 8	[2]						
		$V_{CC} = 2.0 V$		-	52	250	-	300	ns
		$V_{CC} = 4.5 V$		-	19	50	-	60	ns
		$V_{CC} = 5 \text{ V}; \text{ C}_{L} = 15 \text{ pF}$		-	16	-	-	-	ns
		$V_{CC} = 6.0 V$		-	15	43	-	51	ns
t <sub>t</sub>	transition	nQ, nQ; see <u>Figure 7</u>	[3]						
	time	$V_{CC} = 2.0 V$		-	19	95	-	110	ns
		$V_{CC} = 4.5 V$		-	7	19	-	22	ns
		$V_{CC} = 6.0 V$		-	6	16	-	19	ns
t <sub>W</sub>	pulse width	nCP HIGH or LOW; see <u>Figure 7</u>							
		$V_{CC} = 2.0 V$		100	19	-	120	-	ns
		$V_{CC} = 4.5 V$		20	7	-	24	-	ns
		$V_{CC} = 6.0 V$		17	6	-	20	-	ns
		nSD, nRD LOW; see <u>Figure 8</u>							
		$V_{CC} = 2.0 V$		100	19	-	120	-	ns
		$V_{CC} = 4.5 V$		20	7	-	24	-	ns
		$V_{CC} = 6.0 V$		17	6	-	20	-	ns
t <sub>rec</sub>	recovery	nSD, nRD; see <u>Figure 8</u>							
	time	$V_{CC} = 2.0 V$		40	3	-	45	-	ns
		$V_{CC} = 4.5 V$		8	1	-	9	-	ns
		$V_{CC} = 6.0 V$		7	1	-	8	-	ns

# 74HC74; 74HCT74

### Dual D-type flip-flop with set and reset; positive edge-trigger

Symbol	Parameter	Conditions		T <sub>amb</sub> =	: –40 °C to	+85 °C	T <sub>amb</sub> = -40	Unit	
			-	Min	Typ <mark>[1]</mark>	Max	Min	Max	
t <sub>su</sub>	set-up time	nD to nCP; see Figure 7			I				
		V <sub>CC</sub> = 2.0 V		75	6	-	90	-	ns
		V <sub>CC</sub> = 4.5 V		15	2	-	18	-	ns
		V <sub>CC</sub> = 6.0 V		13	2	-	15	-	ns
t <sub>h</sub>	hold time	nD to nCP; see Figure 7							
		V <sub>CC</sub> = 2.0 V		3	-6	-	3	-	ns
		V <sub>CC</sub> = 4.5 V		3	-2	-	3	-	ns
		V <sub>CC</sub> = 6.0 V		3	-2	-	3	-	ns
f <sub>max</sub>	maximum	nCP; see Figure 7							
max	frequency	$V_{CC} = 2.0 V$		4.8	23	-	4.0	-	MHz
		V <sub>CC</sub> = 4.5 V		24	69	-	20	-	MHz
		$V_{CC} = 5 \text{ V}; \text{ C}_{L} = 15 \text{ pF}$		-	76	-	-	-	MHz
		$V_{CC} = 6.0 V$		28	82	-	24	-	MHz
C <sub>PD</sub>	power dissipation capacitance	$C_L = 50 \text{ pF}; \text{ f} = 1 \text{ MHz};$ $V_I = \text{GND to } V_{CC}$	<u>[4]</u>	-	24	-	-	-	pF
74HCT74	-								
t <sub>pd</sub>	propagation delay	nCP to nQ, n <mark>Q</mark> ; see <u>Figure 7</u>	[2]						
		$V_{CC} = 4.5 V$		-	18	44	-	53	ns
		$V_{CC} = 5 \text{ V}; \text{ C}_{L} = 15 \text{ pF}$		-	15	-	-	-	ns
		nSD to nQ, nQ; see Figure 8	[2]						
		$V_{CC} = 4.5 V$		-	23	50	-	60	ns
		$V_{CC} = 5 \text{ V}; \text{ C}_{L} = 15 \text{ pF}$		-	18	-	-	-	ns
		nRD to nQ, nQ; see Figure 8	[2]						
		$V_{CC} = 4.5 V$		-	24	50	-	60	ns
		$V_{CC} = 5 \text{ V}; \text{ C}_{L} = 15 \text{ pF}$		-	18	-	-	-	ns
t <sub>t</sub>	transition	nQ, nQ; see <u>Figure 7</u>	[3]						
	time	V <sub>CC</sub> = 4.5 V		-	7	19	-	22	ns
t <sub>W</sub>	pulse width	nCP HIGH or LOW; see <u>Figure 7</u>							
		V <sub>CC</sub> = 4.5 V		23	9	-	27	-	ns
		nSD, nRD LOW; see <u>Figure 8</u>							
		$V_{CC} = 4.5 V$		20	9	-	24	-	ns
t <sub>rec</sub>	recovery	nSD, nRD; see Figure 8							
	time	V <sub>CC</sub> = 4.5 V		8	1	-	9	-	ns
t <sub>su</sub>	set-up time	nD to nCP; see Figure 7							
	•	V <sub>CC</sub> = 4.5 V		15	5		18		ns

#### Table 8. Dynamic characteristics ... continued

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## 74HC74; 74HCT74

### Dual D-type flip-flop with set and reset; positive edge-trigger

#### Table 8. Dynamic characteristics ...continued

Voltages are referenced to GND (ground = 0 V);  $C_L = 50 \text{ pF}$  unless otherwise specified; for test circuit see Figure 9.

Symbol	Parameter	Conditions		T <sub>amb</sub> = –40 °C to +85 °C			T <sub>amb</sub> =40	Unit	
				Min	Typ <mark>[1]</mark>	Max	Min	Мах	
t <sub>h</sub>	hold time	nD to nCP; see Figure 7							
	$V_{CC} = 4.5 V$		3	-3	-	3	-	ns	
f <sub>max</sub>	ax maximum	nCP; see Figure 7							
	frequency	$V_{CC} = 4.5 V$		22	54	-	18	-	MHz
		$V_{CC} = 5 \text{ V}; \text{ C}_{L} = 15 \text{ pF}$		-	59	-	-	-	MHz
C <sub>PD</sub>	power dissipation capacitance	$C_L$ = 50 pF; f = 1 MHz; V <sub>I</sub> = GND to V <sub>CC</sub> - 1.5 V	<u>[4]</u>	-	29	-	-	-	pF

[1] All typical values are measured at  $T_{amb} = 25 \ ^{\circ}C$ .

[2]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .

 $[3] \quad t_t \mbox{ is the same as } t_{THL} \mbox{ and } t_{TLH}.$ 

[4]  $C_{PD}$  is used to determine the dynamic power dissipation (P<sub>D</sub> in  $\mu$ W).

 $\mathsf{P}_{\mathsf{D}} = \mathsf{C}_{\mathsf{P}\mathsf{D}} \times \mathsf{V}_{\mathsf{C}\mathsf{C}}^2 \times \mathsf{f}_i \times \mathsf{N} + \sum (\mathsf{C}_{\mathsf{L}} \times \mathsf{V}_{\mathsf{C}\mathsf{C}}^2 \times \mathsf{f}_o) \text{ where:}$ 

 $f_i$  = input frequency in MHz;

 $f_o$  = output frequency in MHz;

 $C_L$  = output load capacitance in pF;

 $V_{CC}$  = supply voltage in V;

N = number of inputs switching;

 $\Sigma(C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.

Dual D-type flip-flop with set and reset; positive edge-trigger

## 11. Waveforms



## 74HC74; 74HCT74

Dual D-type flip-flop with set and reset; positive edge-trigger



### Table 9. Measurement points

Туре	Input	Output
	V <sub>M</sub>	V <sub>M</sub>
74HC74	0.5V <sub>CC</sub>	0.5V <sub>CC</sub>
74HCT74	1.3 V	1.3 V

## 74HC74; 74HCT74

### Dual D-type flip-flop with set and reset; positive edge-trigger



#### Table 10. Test data

Туре	Input		Load		Test
	Vi	t <sub>r</sub> , t <sub>f</sub>	CL	RL	
74HC74	V <sub>CC</sub>	6 ns	15 pF, 50 pF	1 kΩ	t <sub>PLH</sub> , t <sub>PHL</sub>
74HCT74	3 V	6 ns	15 pF, 50 pF	1 kΩ	t <sub>PLH</sub> , t <sub>PHL</sub>

## 74HC74; 74HCT74

Dual D-type flip-flop with set and reset; positive edge-trigger

### 12. Package outline



### Fig 10. Package outline SOT27-1 (DIP14)

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Dual D-type flip-flop with set and reset; positive edge-trigger



#### Fig 11. Package outline SOT108-1 (SO14)

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Dual D-type flip-flop with set and reset; positive edge-trigger



#### Fig 12. Package outline SOT337-1 (SSOP14)

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Dual D-type flip-flop with set and reset; positive edge-trigger



#### Fig 13. Package outline SOT402-1 (TSSOP14)

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Dual D-type flip-flop with set and reset; positive edge-trigger



DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm SOT762-1

#### Fig 14. Package outline SOT762-1 (DHVQFN14)

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Dual D-type flip-flop with set and reset; positive edge-trigger

## **13. Abbreviations**

Table 11.	able 11. Abbreviations			
Acronym	Description			
CMOS	Complementary Metal Oxide Semiconductor			
ESD	ElectroStatic Discharge			
HBM	Human Body Model			
MM	Machine Model			
TTL	Transistor-Transistor Logic			

## 14. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT74 v.4	20120827	Product data sheet	-	74HC_HCT74 v.3
Modifications:	<ul> <li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> </ul>			
	<ul> <li>Legal texts</li> </ul>	have been adapted to the	e new company name	where appropriate.
74HC_HCT74 v.3	20030710	Product data sheet	-	74HC_HCT74_CNV v.2
74HC_HCT74_CNV v.2	19980223	Product specification	-	-

Dual D-type flip-flop with set and reset; positive edge-trigger

## **15. Legal information**

### 15.1 Data sheet status

Document status[1][2]	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <a href="http://www.nxp.com">http://www.nxp.com</a>.

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74HC HCT74

### Dual D-type flip-flop with set and reset; positive edge-trigger

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